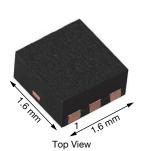
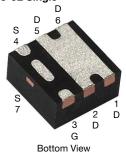
Vishay Siliconix

N-Channel 30 V (D-S) MOSFET

PowerPAK® SC-75-6L Single





Marking Code: AK

PRODUCT SUMMARY	
V _{DS} (V)	30
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.057
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.062
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 2.5 \text{ V}$	0.078
Q _g typ. (nC)	3.5
I _D (A) ^{a, c}	6
Configuration	Single

FEATURES

- TrenchFET® power MOSFET
- Thermally enhanced PowerPAK® SC-70 package
 - Small footprint area
 - Low on-resistance
- Typical ESD protection: 1500 V (HBM)
- 100 % R_q tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

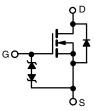
APPLICATIONS

- · Portable devices such as smart phones, tablet PCs and mobile computing
 - Load switch
 - DC/DC converter
 - Power management



RoHS COMPLIANT

HALOGEN FREE



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK SC-75
Lead (Pb)-free and halogen-free	SiB4316EDK-T1-GE3

ABSOLUTE MAXIMUM RATING	S (T _A = 25 °C, unle	ss otherwise no	oted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	30	V	
Gate-source voltage		V _{GS}	± 12	l v	
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		6 ^a		
	T _C = 70 °C] . [6 ^a	1	
	T _A = 25 °C	I _D	4.5 ^{b, c}	А	
	T _A = 70 °C	1	3.6 ^{b, c}		
Pulsed drain current (t = 300 μs)		I _{DM}	15		
Continuous source-drain diode current	T _C = 25 °C	I _S	6 ^a		
	T _A = 25 °C		1.63 ^{b, c}]	
Maximum power dissipation	T _C = 25 °C		10		
	T _C = 70 °C] _ [6.4	14/	
	T _A = 25 °C	P _D	1.9 ^{5 b, c}	W	
	T _A = 70 °C	1	1.25 ^{b, c}	1	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) d,e			260		

THERMAL RESISTANCE RATINGS							
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT		
Maximum junction-to-ambient b, f	t ≤ 5 s R _{thJA}		51	64	°C/W		
Maximum junction-to-case (drain)	Steady state	R_{thJC}	10	12.5	- C/W		

Notes

- a. Package limited
- b. Surface mounted on 1" x 1" FR4 board
- See solder profile (www.vishay.com/doc?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state condition is 100 °C/W

For technical questions, contact: pmostechsupport@vishay.com



www.vishay.com

Vishay Siliconix

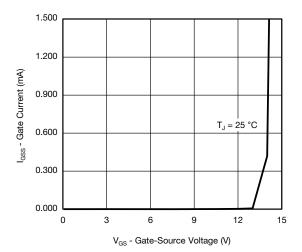
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				•			
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	34	-	mV/°C	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$	-	-3.3	-		
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.6	-	1.4	V	
Cata aguraa laakaga		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 0.5		
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	-				
Zara gata valtaga duain avurant		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	- μΑ	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10		
Drain-source on-state resistance ^a		V _{GS} = 10 V, I _D = 4 A	-	0.047	0.057		
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$	-	0.051	0.062	Ω	
		$V_{GS} = 2.5 \text{ V}, I_D = 1 \text{ A}$	-	0.062	0.078		
Forward transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 3 A	-	13	-	S	
Dynamic ^b							
Total gate aboves	0	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 4 A	-	7.5	12	nC	
Total gate charge	Qg		-	3.5	5.5		
Gate-source charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 4 \text{ A}$	-	1.8	-		
Gate-drain charge	Q _{gd}		-	0.7	-		
Gate resistance	Rg	f = 1 MHz	0.6	3.3	6.6	Ω	
Turn-on delay time	t _{d(on)}		-	20	40		
Rise time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 4.7 \Omega$	-	60	120		
Turn-off delay time	t _{d(off)}	$I_D \cong 3.2 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	25	50		
Fall time	t _f		-	45	90		
Turn-on delay time	t _{d(on)}		-	1.5	5	ns	
Rise time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 4.7 \Omega$	-	30	60		
Turn-off delay time	t _{d(off)}	$I_D \cong 3.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	15	30		
Fall time	t _f		-	50	100		
Drain-Source Body Diode Characteristi	cs						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	3.9	^	
Pulse diode forward current	I _{SM}		-	-	15	Α	
Body diode voltage	V _{SD}	I _S = 3.2 A, V _{GS} = 0 V	-	0.87	1.2	V	
Body diode reverse recovery time	t _{rr}		-	10	20	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F=3.2$ A, dl/dt = 100 A/ μ s, $T_J=25$ °C	-	4	10	nC	
Reverse recovery fall time	ta		-	5.3	-		
Reverse recovery rise time	t _b		_	4.6	-	ns	

Notes

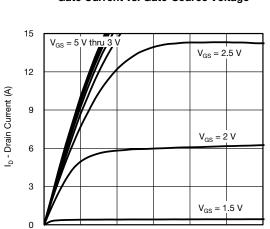
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





Gate Current vs. Gate-Source Voltage

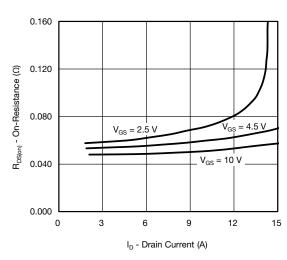


V_{DS} - Drain-to-Source Voltage (V) Output Characteristics

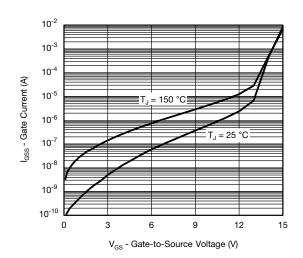
1.5

2.5

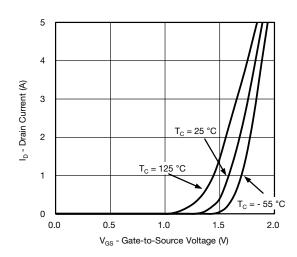
3.0



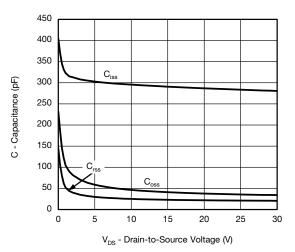
On-Resistance vs. Drain Current and Gate Voltage



Gate Current vs. Gate-Source Voltage



Transfer Characteristics



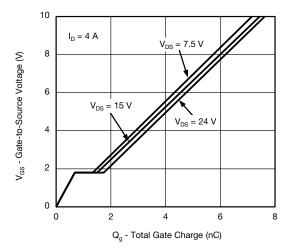
Capacitance

0.0

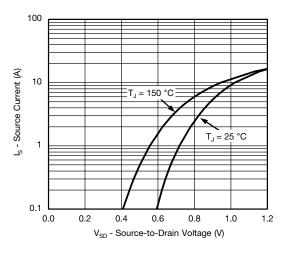
0.5

1.0

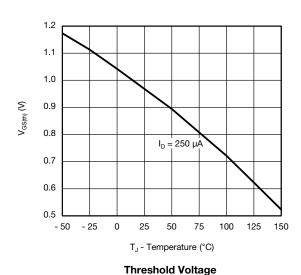


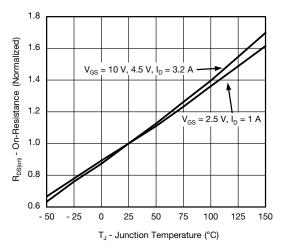


Gate Charge

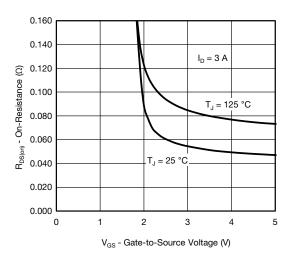


Source-Drain Diode Forward Voltage

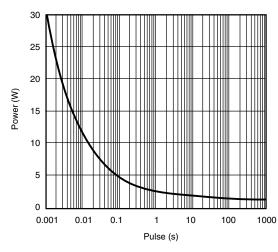




On-Resistance vs. Junction Temperature

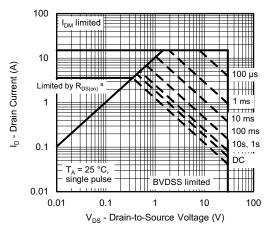


On-Resistance vs. Gate-to-Source Voltage

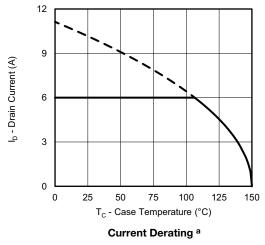


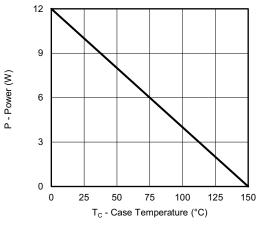
Single Pulse Power (Junction-to-Ambient)





Safe Operating Area, Junction-to-Ambient



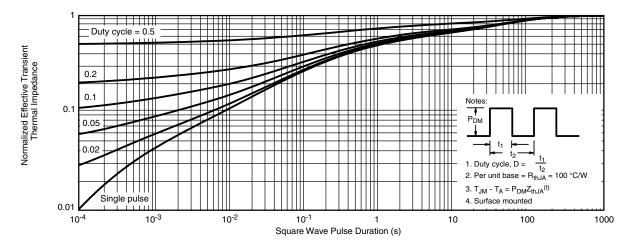


Power Derating

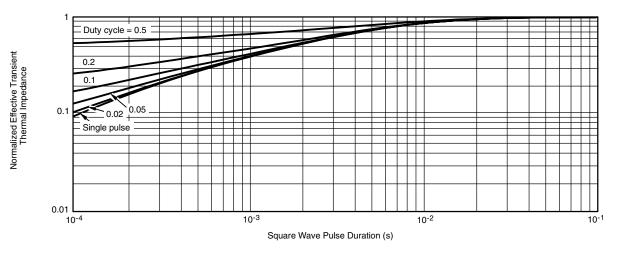
Note

a. The power dissipation P_D is based on T_J (max.) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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